



PRINTED CIRCUIT BOARDS
INTERCONNECTION CARRIERS

State of the Art: PCB's

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01

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1/1

Schematic Key for Multilayer and HDI-Technology Build-Ups

| a | b | c | d | e | f | g + h + i |
|---|---|---|---|---|---|-----------|
|---|---|---|---|---|---|-----------|

04 152 FR4 35 L10.35 P18_10 S1

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_152_FR4_35_L10.35_p18_10_s1

| Layers | in μ | Material | Build-Up | Assembly |
|-----------------|-----------|----------|--------------------------------|----------|
| Layer-1 | 35 μ | Copper | | A1 B |
| | 100 μ | Prepreg | (100 μ PrePreg-Type: 2125) | |
| | 180 μ | Prepreg | (180 μ PrePreg-Type: 7628) | |
| | 180 μ | Prepreg | | |
| | 180 μ | Prepreg | | |
| Layer-2 | 35 μ | Copper | | |
| | 100 μ | L-FR4 | | |
| Layer-3 | 35 μ | Copper | | |
| | 180 μ | Prepreg | | |
| | 180 μ | Prepreg | | |
| | 180 μ | Prepreg | | |
| Layer-99 | 100 μ | Prepreg | | |
| | 35 μ | Copper | | |

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